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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	16
Number of Macrocells	256
Number of Gates	-
Number of I/O	160
Operating Temperature	-40°C ~ 105°C (TJ)
Mounting Type	Surface Mount
Package / Case	256-LBGA
Supplier Device Package	256-FTBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4256v-10ft256bi

Table 2. ispMACH 4000Z Family Selection Guide

	ispMACH 4032ZC	ispMACH 4064ZC	ispMACH 4128ZC	ispMACH 4256ZC
Macrocells	32	64	128	256
I/O + Dedicated Inputs	32+4/32+4	32+4/32+12/ 64+10/64+10	64+10/96+4	64+10/96+6/ 128+4
t _{PD} (ns)	3.5	3.7	4.2	4.5
t _S (ns)	2.2	2.5	2.7	2.9
t _{CO} (ns)	3.0	3.2	3.5	3.8
f _{MAX} (MHz)	267	250	220	200
Supply Voltage (V)	1.8	1.8	1.8	1.8
Max. Standby I _{cc} (μ A)	20	25	35	55
Pins/Package	48 TQFP 56 csBGA	48 TQFP 56 csBGA 100 TQFP 132 csBGA	100 TQFP 132csBGA	100 TQFP 132 csBGA 176 TQFP

ispMACH 4000 Introduction

The high performance ispMACH 4000 family from Lattice offers a SuperFAST CPLD solution. The family is a blend of Lattice's two most popular architectures: the ispLSI® 2000 and ispMACH 4A. Retaining the best of both families, the ispMACH 4000 architecture focuses on significant innovations to combine the highest performance with low power in a flexible CPLD family.

The ispMACH 4000 combines high speed and low power with the flexibility needed for ease of design. With its robust Global Routing Pool and Output Routing Pool, this family delivers excellent First-Time-Fit, timing predictability, routing, pin-out retention and density migration.

The ispMACH 4000 family offers densities ranging from 32 to 512 macrocells. There are multiple density-I/O combinations in Thin Quad Flat Pack (TQFP), Chip Scale BGA (csBGA) and Fine Pitch Thin BGA (ftBGA) packages ranging from 44 to 256 pins/balls. Table 1 shows the macrocell, package and I/O options, along with other key parameters.

The ispMACH 4000 family has enhanced system integration capabilities. It supports 3.3V (4000V), 2.5V (4000B) and 1.8V (4000C/Z) supply voltages and 3.3V, 2.5V and 1.8V interface voltages. Additionally, inputs can be safely driven up to 5.5V when an I/O bank is configured for 3.3V operation, making this family 5V tolerant. The ispMACH 4000 also offers enhanced I/O features such as slew rate control, PCI compatibility, bus-keeper latches, pull-up resistors, pull-down resistors, open drain outputs and hot socketing. The ispMACH 4000 family members are 3.3V/2.5V/1.8V in-system programmable through the IEEE Standard 1532 interface. IEEE Standard 1149.1 boundary scan testing capability also allows product testing on automated test equipment. The 1532 interface signals TCK, TMS, TDI and TDO are referenced to V_{CC} (logic core).

Overview

The ispMACH 4000 devices consist of multiple 36-input, 16-macrocell Generic Logic Blocks (GLBs) interconnected by a Global Routing Pool (GRP). Output Routing Pools (ORPs) connect the GLBs to the I/O Blocks (IOBs), which contain multiple I/O cells. This architecture is shown in Figure 1.

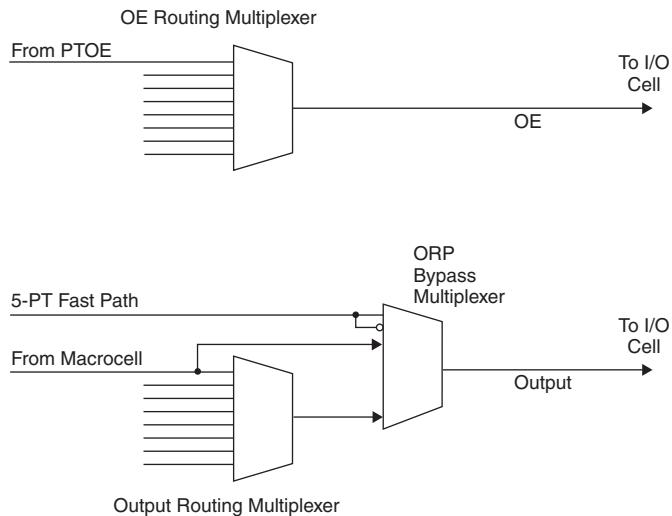
Output Routing Pool (ORP)

The Output Routing Pool allows macrocell outputs to be connected to any of several I/O cells within an I/O block. This provides greater flexibility in determining the pinout and allows design changes to occur without affecting the pinout. The output routing pool also provides a parallel capability for routing macrocell-level OE product terms. This allows the OE product term to follow the macrocell output as it is switched between I/O cells. Additionally, the output routing pool allows the macrocell output or true and complement forms of the 5-PT bypass signal to bypass the output routing multiplexers and feed the I/O cell directly. The enhanced ORP of the ispMACH 4000 family consists of the following elements:

- Output Routing Multiplexers
- OE Routing Multiplexers
- Output Routing Pool Bypass Multiplexers

Figure 7 shows the structure of the ORP from the I/O cell perspective. This is referred to as an ORP slice. Each ORP has as many ORP slices as there are I/O cells in the corresponding I/O block.

Figure 7. ORP Slice



Output Routing Multiplexers

The details of connections between the macrocells and the I/O cells vary across devices and within a device dependent on the maximum number of I/Os available. Tables 5-9 provide the connection details.

Table 6. ORP Combinations for I/O Blocks with 8 I/Os

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M2, M3, M4, M5, M6, M7, M8, M9
I/O 2	M4, M5, M6, M7, M8, M9, M10, M11
I/O 3	M6, M7, M8, M9, M10, M11, M12, M13
I/O 4	M8, M9, M10, M11, M12, M13, M14, M15
I/O 5	M10, M11, M12, M13, M14, M15, M0, M1
I/O 6	M12, M13, M14, M15, M0, M1, M2, M3
I/O 7	M14, M15, M0, M1, M2, M3, M4, M5

Supply Current, ispMACH 4000V/B/C**Over Recommended Operating Conditions**

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
ispMACH 4032V/B/C						
ICC ^{1,2,3}	Operating Power Supply Current	Vcc = 3.3V	—	11.8	—	mA
		Vcc = 2.5V	—	11.8	—	mA
		Vcc = 1.8V	—	1.8	—	mA
ICC ⁴	Standby Power Supply Current	Vcc = 3.3V	—	11.3	—	mA
		Vcc = 2.5V	—	11.3	—	mA
		Vcc = 1.8V	—	1.3	—	mA
ispMACH 4064V/B/C						
ICC ^{1,2,3}	Operating Power Supply Current	Vcc = 3.3V	—	12	—	mA
		Vcc = 2.5V	—	12	—	mA
		Vcc = 1.8V	—	2	—	mA
ICC ⁵	Standby Power Supply Current	Vcc = 3.3V	—	11.5	—	mA
		Vcc = 2.5V	—	11.5	—	mA
		Vcc = 1.8V	—	1.5	—	mA
ispMACH 4128V/B/C						
ICC ^{1,2,3}	Operating Power Supply Current	Vcc = 3.3V	—	12	—	mA
		Vcc = 2.5V	—	12	—	mA
		Vcc = 1.8V	—	2	—	mA
ICC ⁴	Standby Power Supply Current	Vcc = 3.3V	—	11.5	—	mA
		Vcc = 2.5V	—	11.5	—	mA
		Vcc = 1.8V	—	1.5	—	mA
ispMACH 4256V/B/C						
I _{CC} ^{1,2,3}	Operating Power Supply Current	Vcc = 3.3V	—	12.5	—	mA
		Vcc = 2.5V	—	12.5	—	mA
		Vcc = 1.8V	—	2.5	—	mA
I _{CC} ⁴	Standby Power Supply Current	Vcc = 3.3V	—	12	—	mA
		Vcc = 2.5V	—	12	—	mA
		Vcc = 1.8V	—	2	—	mA
ispMACH 4384V/B/C						
I _{CC} ^{1,2,3}	Operating Power Supply Current	Vcc = 3.3V	—	13.5	—	mA
		Vcc = 2.5V	—	13.5	—	mA
		Vcc = 1.8V	—	3.5	—	mA
I _{CC} ⁴	Standby Power Supply Current	Vcc = 3.3V	—	12.5	—	mA
		Vcc = 2.5V	—	12.5	—	mA
		Vcc = 1.8V	—	2.5	—	mA
ispMACH 4512V/B/C						
I _{CC} ^{1,2,3}	Operating Power Supply Current	Vcc = 3.3V	—	14	—	mA
		Vcc = 2.5V	—	14	—	mA
		Vcc = 1.8V	—	4	—	mA

Supply Current, ispMACH 4000V/B/C (Cont.)

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{CC}^4	Standby Power Supply Current	Vcc = 3.3V	—	13	—	mA
		Vcc = 2.5V	—	13	—	mA
		Vcc = 1.8V	—	3	—	mA

- 1. $T_A = 25^\circ\text{C}$, frequency = 1.0 MHz.
- 2. Device configured with 16-bit counters.
- 3. I_{CC} varies with specific device configuration and operating frequency.
- 4. $T_A = 25^\circ\text{C}$

Supply Current, ispMACH 4000Z

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
ispMACH 4032ZC						
$ICC^{1, 2, 3, 5}$	Operating Power Supply Current	Vcc = 1.8V, $T_A = 25^\circ\text{C}$	—	50	—	μA
		Vcc = 1.9V, $T_A = 70^\circ\text{C}$	—	58	—	μA
		Vcc = 1.9V, $T_A = 85^\circ\text{C}$	—	60	—	μA
		Vcc = 1.9V, $T_A = 125^\circ\text{C}$	—	70	—	μA
$ICC^{4, 5}$	Standby Power Supply Current	Vcc = 1.8V, $T_A = 25^\circ\text{C}$	—	10	—	μA
		Vcc = 1.9V, $T_A = 70^\circ\text{C}$	—	13	20	μA
		Vcc = 1.9V, $T_A = 85^\circ\text{C}$	—	15	25	μA
		Vcc = 1.9V, $T_A = 125^\circ\text{C}$	—	22	—	μA
ispMACH 4064ZC						
$ICC^{1, 2, 3, 5}$	Operating Power Supply Current	Vcc = 1.8V, $T_A = 25^\circ\text{C}$	—	80	—	μA
		Vcc = 1.9V, $T_A = 70^\circ\text{C}$	—	89	—	μA
		Vcc = 1.9V, $T_A = 85^\circ\text{C}$	—	92	—	μA
		Vcc = 1.9V, $T_A = 125^\circ\text{C}$	—	109	—	μA
$ICC^{4, 5}$	Standby Power Supply Current	Vcc = 1.8V, $T_A = 25^\circ\text{C}$	—	11	—	μA
		Vcc = 1.9V, $T_A = 70^\circ\text{C}$	—	15	25	μA
		Vcc = 1.9V, $T_A = 85^\circ\text{C}$	—	18	35	μA
		Vcc = 1.9V, $T_A = 125^\circ\text{C}$	—	37	—	μA
ispMACH 4128ZC						
$ICC^{1, 2, 3, 5}$	Operating Power Supply Current	Vcc = 1.8V, $T_A = 25^\circ\text{C}$	—	168	—	μA
		Vcc = 1.9V, $T_A = 70^\circ\text{C}$	—	190	—	μA
		Vcc = 1.9V, $T_A = 85^\circ\text{C}$	—	195	—	μA
		Vcc = 1.9V, $T_A = 125^\circ\text{C}$	—	212	—	μA
$ICC^{4, 5}$	Standby Power Supply Current	Vcc = 1.8V, $T_A = 25^\circ\text{C}$	—	12	—	μA
		Vcc = 1.9V, $T_A = 70^\circ\text{C}$	—	16	35	μA
		Vcc = 1.9V, $T_A = 85^\circ\text{C}$	—	19	50	μA
		Vcc = 1.9V, $T_A = 125^\circ\text{C}$	—	42	—	μA

I/O DC Electrical Characteristics

Over Recommended Operating Conditions

Standard	V _{IL}		V _{IH}		V _{OL} Max (V)	V _{OH} Min (V)	I _{OL} ¹ (mA)	I _{OH} ¹ (mA)
	Min (V)	Max (V)	Min (V)	Max (V)				
LV TTL	-0.3	0.80	2.0	5.5	0.40	V _{CCO} - 0.40	8.0	-4.0
					0.20	V _{CCO} - 0.20	0.1	-0.1
LVCMOS 3.3	-0.3	0.80	2.0	5.5	0.40	V _{CCO} - 0.40	8.0	-4.0
					0.20	V _{CCO} - 0.20	0.1	-0.1
LVCMOS 2.5	-0.3	0.70	1.70	3.6	0.40	V _{CCO} - 0.40	8.0	-4.0
					0.20	V _{CCO} - 0.20	0.1	-0.1
LVCMOS 1.8 (4000V/B)	-0.3	0.63	1.17	3.6	0.40	V _{CCO} - 0.45	2.0	-2.0
					0.20	V _{CCO} - 0.20	0.1	-0.1
LVCMOS 1.8 (4000C/Z)	-0.3	0.35 * V _{CC}	0.65 * V _{CC}	3.6	0.40	V _{CCO} - 0.45	2.0	-2.0
					0.20	V _{CCO} - 0.20	0.1	-0.1
PCI 3.3 (4000V/B)	-0.3	1.08	1.5	5.5	0.1 V _{CCO}	0.9 V _{CCO}	1.5	-0.5
PCI 3.3 (4000C/Z)	-0.3	0.3 * 3.3 * (V _{CC} / 1.8)	0.5 * 3.3 * (V _{CC} / 1.8)	5.5	0.1 V _{CCO}	0.9 V _{CCO}	1.5	-0.5

1. The average DC current drawn by I/Os between adjacent bank GND connections, or between the last GND in an I/O bank and the end of the I/O bank, as shown in the logic signals connection table, shall not exceed $n \cdot 8\text{mA}$. Where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.

ispMACH 4000Z External Switching Characteristics (Cont.)**Over Recommended Operating Conditions**

Parameter	Description ^{1, 2, 3}	-45		-5		-75		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{PD}	5-PT bypass combinatorial propagation delay	—	4.5	—	5.0	—	7.5	ns
t _{PD_MG}	20-PT combinatorial propagation delay through macrocell	—	5.8	—	6.0	—	8.0	ns
t _S	GLB register setup time before clock	2.9	—	3.0	—	4.5	—	ns
t _{ST}	GLB register setup time before clock with T-type register	3.1	—	3.2	—	4.7	—	ns
t _{SIR}	GLB register setup time before clock, input register path	1.3	—	1.3	—	1.4	—	ns
t _{SIRZ}	GLB register setup time before clock with zero hold	2.6	—	2.6	—	2.7	—	ns
t _H	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	ns
t _{HT}	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	ns
t _{HIR}	GLB register hold time after clock, input register path	1.3	—	1.3	—	1.3	—	ns
t _{HIRZ}	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	ns
t _{CO}	GLB register clock-to-output delay	—	3.8	—	4.2	—	4.5	ns
t _R	External reset pin to output delay	—	7.5	—	7.5	—	9.0	ns
t _{RW}	External reset pulse duration	2.0	—	2.0	—	4.0	—	ns
t _{PTOE/DIS}	Input to output local product term output enable/disable	—	8.2	—	8.5	—	9.0	ns
t _{GPTOE/DIS}	Input to output global product term output enable/disable	—	10.0	—	10.0	—	10.5	ns
t _{GOE/DIS}	Global OE input to output enable/disable	—	5.5	—	6.0	—	7.0	ns
t _{CW}	Global clock width, high or low	1.8	—	2.0	—	2.8	—	ns
t _{GW}	Global gate width low (for low transparent) or high (for high transparent)	1.8	—	2.0	—	2.8	—	ns
t _{WIR}	Input register clock width, high or low	1.8	—	2.0	—	2.8	—	ns
f _{MAX} ⁴	Clock frequency with internal feedback	—	200	—	200	—	168	MHz
f _{MAX} (Ext.)	clock frequency with external feedback, [1 / (t _S + t _{CO})]	—	150	—	139	—	111	MHz

1. Timing numbers are based on default LVCMS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.

Timing v.2.2

2. Measured using standard switching GRP loading of 1 and 1 output switching.

3. Pulse widths and clock widths less than minimum will cause unknown behavior.

4. Standard 16-bit counter using GRP feedback.

ispMACH 4000Z Internal Timing Parameters (Cont.)

Over Recommended Operating Conditions

Parameter	Description	-45		-5		-75		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
In/Out Delays								
t_{IN}	Input Buffer Delay	—	0.95	—	1.25	—	1.80	ns
t_{GOE}	Global OE Pin Delay	—	3.00	—	3.50	—	4.30	ns
t_{GCLK_IN}	Global Clock Input Buffer Delay	—	1.95	—	2.05	—	2.15	ns
t_{BUF}	Delay through Output Buffer	—	1.10	—	1.00	—	1.30	ns
t_{EN}	Output Enable Time	—	2.50	—	2.50	—	2.70	ns
t_{DIS}	Output Disable Time	—	2.50	—	2.50	—	2.70	ns
Routing/GLB Delays								
t_{ROUTE}	Delay through GRP	—	2.25	—	2.05	—	2.50	ns
t_{MCELL}	Macrocell Delay	—	0.65	—	0.65	—	1.00	ns
t_{INREG}	Input Buffer to Macrocell Register Delay	—	1.00	—	1.00	—	1.00	ns
t_{FBK}	Internal Feedback Delay	—	0.35	—	0.05	—	0.05	ns
t_{PD_b}	5-PT Bypass Propagation Delay	—	0.20	—	0.70	—	1.90	ns
t_{PDI}	Macrocell Propagation Delay	—	0.45	—	0.65	—	1.00	ns
Register/Latch Delays								
t_S	D-Register Setup Time (Global Clock)	1.00	—	1.10	—	1.35	—	ns
t_{S_PT}	D-Register Setup Time (Product Term Clock)	2.10	—	1.90	—	2.45	—	ns
t_{ST}	T-Register Setup Time (Global Clock)	1.20	—	1.30	—	1.55	—	ns
t_{ST_PT}	T-register Setup Time (Product Term Clock)	2.30	—	2.10	—	2.75	—	ns
t_H	D-Register Hold Time	1.90	—	1.90	—	3.15	—	ns
t_{HT}	T-Resister Hold Time	1.90	—	1.90	—	3.15	—	ns
t_{SIR}	D-Input Register Setup Time (Global Clock)	1.30	—	1.10	—	0.75	—	ns
t_{SIR_PT}	D-Input Register Setup Time (Product Term Clock)	1.45	—	1.45	—	1.45	—	ns
t_{HIR}	D-Input Register Hold Time (Global Clock)	1.30	—	1.50	—	1.95	—	ns
t_{HIR_PT}	D-Input Register Hold Time (Product Term Clock)	1.00	—	1.00	—	1.18	—	ns
t_{COi}	Register Clock to Output/Feedback MUX Time	—	0.75	—	1.15	—	1.05	ns
t_{CES}	Clock Enable Setup Time	2.00	—	2.00	—	2.00	—	ns
t_{CEH}	Clock Enable Hold Time	0.00	—	0.00	—	0.00	—	ns
t_{SL}	Latch Setup Time (Global Clock)	1.00	—	1.00	—	1.65	—	ns
t_{SL_PT}	Latch Setup Time (Product Term Clock)	2.10	—	1.90	—	2.15	—	ns
t_{HL}	Latch Hold Time	2.00	—	2.00	—	1.17	—	ns
t_{GOi}	Latch Gate to Output/Feedback MUX Time	—	0.33	—	0.33	—	0.33	ns
t_{PDLi}	Propagation Delay through Transparent Latch to Output/Feedback MUX	—	0.25	—	0.25	—	0.25	ns
t_{SRi}	Asynchronous Reset or Set to Output/Feedback MUX Delay	—	0.97	—	0.97	—	0.28	ns
t_{SRR}	Asynchronous Reset or Set Recovery Delay	—	1.80	—	1.80	—	1.67	ns
Control Delays								
t_{BCLK}	GLB PT Clock Delay	—	1.55	—	1.55	—	1.25	ns
t_{PTCLK}	Macrocell PT Clock Delay	—	1.55	—	1.55	—	1.25	ns
t_{BSR}	GLB PT Set/Reset Delay	—	1.83	—	1.83	—	1.83	ns
t_{PTSR}	Macrocell PT Set/Reset Delay	—	1.83	—	1.83	—	2.72	ns
t_{GPTOE}	Global PT OE Delay	—	4.30	—	4.20	—	3.50	ns

ispMACH 4000V/B/C Timing Adders¹ (Cont.)

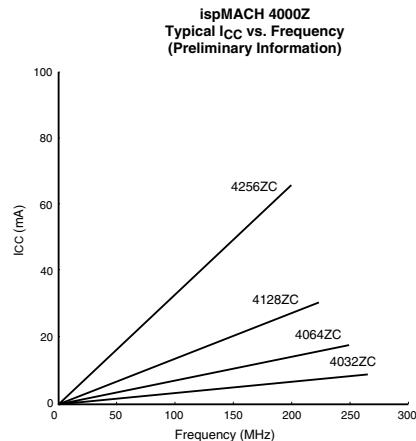
Adder Type	Base Parameter	Description	-5		-75		-10		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
Optional Delay Adders									
t_{INDIO}	t_{INREG}	Input register delay	—	1.00	—	1.00	—	1.00	ns
t_{EXP}	t_{MCELL}	Product term expander delay	—	0.33	—	0.33	—	0.33	ns
t_{ORP}	—	Output routing pool delay	—	0.05	—	0.05	—	0.05	ns
t_{BLA}	t_{ROUTE}	Additional block loading adder	—	0.05	—	0.05	—	0.05	ns
t_{IOI} Input Adjusters									
LVTTL_in	t_{IN} , t_{GCLK_IN} , t_{GOE}	Using LVTTL standard	—	0.60	—	0.60	—	0.60	ns
LVCMOS33_in	t_{IN} , t_{GCLK_IN} , t_{GOE}	Using LVCMOS 3.3 standard	—	0.60	—	0.60	—	0.60	ns
LVCMOS25_in	t_{IN} , t_{GCLK_IN} , t_{GOE}	Using LVCMOS 2.5 standard	—	0.60	—	0.60	—	0.60	ns
LVCMOS18_in	t_{IN} , t_{GCLK_IN} , t_{GOE}	Using LVCMOS 1.8 standard	—	0.00	—	0.00	—	0.00	ns
PCI_in	t_{IN} , t_{GCLK_IN} , t_{GOE}	Using PCI compatible input	—	0.60	—	0.60	—	0.60	ns
t_{IOO} Output Adjusters									
LVTTL_out	t_{BUF} , t_{EN} , t_{DIS}	Output configured as TTL buffer	—	0.20	—	0.20	—	0.20	ns
LVCMOS33_out	t_{BUF} , t_{EN} , t_{DIS}	Output configured as 3.3V buffer	—	0.20	—	0.20	—	0.20	ns
LVCMOS25_out	t_{BUF} , t_{EN} , t_{DIS}	Output configured as 2.5V buffer	—	0.10	—	0.10	—	0.10	ns
LVCMOS18_out	t_{BUF} , t_{EN} , t_{DIS}	Output configured as 1.8V buffer	—	0.00	—	0.00	—	0.00	ns
PCI_out	t_{BUF} , t_{EN} , t_{DIS}	Output configured as PCI compatible buffer	—	0.20	—	0.20	—	0.20	ns
Slow Slew	t_{BUF} , t_{EN}	Output configured for slow slew rate	—	1.00	—	1.00	—	1.00	ns

Note: Open drain timing is the same as corresponding LVCMOS timing.

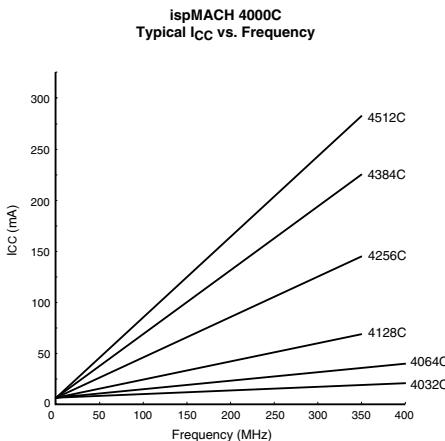
Timing v.3.2

1. Refer to TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#) for information regarding use of these adders.

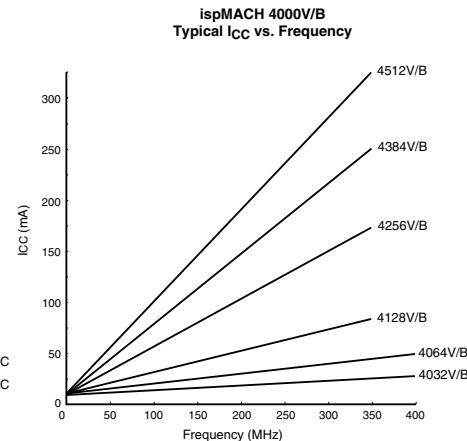
Power Consumption



Note: The devices are configured with maximum number of 16-bit counters, typical current at 1.8V, 25°C.



Note: The devices are configured with maximum number of 16-bit counters, typical current at 1.8V, 25°C.



Note: The devices are configured with maximum number of 16-bit counters, typical current at 3.3V, 2.5V, 25°C.

Power Estimation Coefficients¹

Device	A	B
ispMACH 4032V/B	11.3	0.010
ispMACH 4032C	1.3	0.010
ispMACH 4064V/B	11.5	0.010
ispMACH 4064C	1.5	0.010
ispMACH 4128V/B	11.5	0.011
ispMACH 4128C	1.5	0.011
ispMACH 4256V/B	12	0.011
ispMACH 4256C	2	0.011
ispMACH 4384V/B	12.5	0.013
ispMACH 4384C	2.5	0.013
ispMACH 4512V/B	13	0.013
ispMACH 4512C	3	0.013
ispMACH 4032ZC	0.010	0.010
ispMACH 4064ZC	0.011	0.010
ispMACH 4128ZC	0.012	0.010
ispMACH 4256ZC	0.013	0.010

- For further information about the use of these coefficients, refer to TN1005, [Power Estimation in ispMACH 4000V/B/C/Z Devices](#).

ispMACH 4000V/B/C/Z Power Supply and NC Connections¹ (Cont.)

Signal	132-ball csBGA ⁷	144-pin TQFP ⁴	176-pin TQFP ⁴	256-ball ftBGA/fpBGA ^{2, 3, 7, 9}
VCC	P1, A14, B7, N8	36, 57, 108, 129	42, 69, 88, 130, 157, 176	B2, B15, G8, G9, K8, K9, R2, R15
VCCO0 VCCO (Bank 0)	G3, P5, C1 ⁸ , M2 ⁸ , C5	3, 19, 34, 47, 136	4, 22, 40, 56, 166	D6, F4, H7, J7, L4, N6
VCCO1 VCCO (Bank 1)	M10, M14 ⁸ , H12, A10, C13 ⁸	64, 75, 91, 106, 119	78, 92, 110, 128, 144	D11, F13, H10, J10, L13, N11
GND	B1, P2, N14, A13	1, 37, 73, 109	2, 46 ⁵ , 65, 90, 134, 153	A1, A16, C6, C11, F3, F14, G7, G10, H8, H9, J8, J9, K7, K10, L3, L14, P6, P11, T1, T16
GND (Bank 0)	E2, K2, N4, B4	10, 18 ⁶ , 27, 46, 127, 137	13, 31, 55, 155, 167	
GND (Bank 1)	N11, K13, E13, B11	55, 65, 82, 90 ⁶ , 99, 118	67, 79, 101, 119, 143	
NC	4064Z: C1, C3, E1, E3, H2, J3, K1, M2, M4, N5, P7, P8, M8, P10, P11, P14, M12, K14, K12, G13, G14, E14, C13, B13, B10, C10, A7, B5, A5, A4, A1 4128Z: P8, A7	4128V: 17, 20, 38, 45, 72, 89, 92, 110, 117, 144 4256V: 18, 90	1, 43, 44, 45, 89, 131, 132, 133	4256V/B/C, 128 I/O: A4, A5, A6, A11, A12, A13, A15, B5, B6, B11, B12, B14, C7, D1, D4, D5, D10, D12, D16, E1, E2, E4, E5, E7, E10, E13, E14, E15, E16, F1, F2, F15, F16, G1, G4, G5, G6, G12, G13, G14, J11, K3, K4, K15, L1, L2, L12, L15, L16, M1, M2, M3, M4, M5, M12, M13, M15, M16, N1, N2, N7, N10, N12, N14, P5, P12, R4, R5, R6, R11, R12, R16, T2, T4, T5, T6, T11, T12, T13, T15 4256V/B/C, 160 I/O: A5, A12, A15, B5, B6, B11, B12, B14, D4, D5, D12, E1, E4, E5, E13, E15, E16, F1, F2, F15, G1, G5, G12, G14, L1, L2, L12, L15, L16, M1, M2, M3, M12, M16, N1, N12, N14, P5, P12, R4, R5, R6, R11, R12, R16, T4, T5, T12, T15 4384V/B/C: B5, B12, D5, D12, E1, E15, E16, F2, L12, M1, M2, M16, N12, R5, R12, T4 4512V/B/C: None

1. All grounds must be electrically connected at the board level. However, for the purposes of I/O current loading, grounds are associated with the bank shown.
2. Internal GNDs and I/O GNDs (Bank 0/1) are connected inside package.
3. V_{CCO} balls connect to two power planes within the package, one for V_{CCO0} and one for V_{CCO1}.
4. Pin orientation follows the conventional order from pin 1 marking of the top side view and counter-clockwise.
5. ispMACH 4384V/B/C pin 46 is tied to GND (Bank 0).
6. ispMACH 4128V only.
7. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.
8. ispMACH 4128Z and 4256Z only. NC for ispMACH 4064Z.
9. Use 256 ftBGA package for all new designs. Refer to PCN#14A-07 for 256 fpBGA package discontinuance.

**ispMACH 4032V/B/C and 4064V/B/C Logic Signal Connections:
44-Pin TQFP**

Pin Number	Bank Number	ispMACH 4032V/B/C		ispMACH 4064V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
1	-	TDI	-	TDI	-
2	0	A5	A^5	A10	A^5
3	0	A6	A^6	A12	A^6
4	0	A7	A^7	A14	A^7
5	0	GND (Bank 0)	-	GND (Bank 0)	-
6	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
7	0	A8	A^8	B0	B^0
8	0	A9	A^9	B2	B^1
9	0	A10	A^10	B4	B^2
10	-	TCK	-	TCK	-
11	-	VCC	-	VCC	-
12	-	GND	-	GND	-
13	0	A12	A^12	B8	B^4
14	0	A13	A^13	B10	B^5
15	0	A14	A^14	B12	B^6
16	0	A15	A^15	B14	B^7
17	1	CLK2/I	-	CLK2/I	-
18	1	B0	B^0	C0	C^0
19	1	B1	B^1	C2	C^1
20	1	B2	B^2	C4	C^2
21	1	B3	B^3	C6	C^3
22	1	B4	B^4	C8	C^4
23	-	TMS	-	TMS	-
24	1	B5	B^5	C10	C^5
25	1	B6	B^6	C12	C^6
26	1	B7	B^7	C14	C^7
27	1	GND (Bank 1)	-	GND (Bank 1)	-
28	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
29	1	B8	B^8	D0	D^0
30	1	B9	B^9	D2	D^1
31	1	B10	B^10	D4	D^2
32	-	TDO	-	TDO	-
33	-	VCC	-	VCC	-
34	-	GND	-	GND	-
35	1	B12	B^12	D8	D^4
36	1	B13	B^13	D10	D^5
37	1	B14	B^14	D12	D^6
38	1	B15/GOE1	B^15	D14/GOE1	D^7
39	0	CLK0/I	-	CLK0/I	-
40	0	A0/GOE0	A^0	A0/GOE0	A^0
41	0	A1	A^1	A2	A^1

**ispMACH 4064V/B/C/Z, 4128V/B/C/Z, 4256V/B/C/Z Logic Signal Connections:
100-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4064V/B/C/Z		ispMACH 4128V/B/C/Z		ispMACH 4256V/B/C/Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
42	1	C1	C^1	E2	E^1	I6	I^1
43	1	C2	C^2	E4	E^2	I10	I^2
44	1	C3	C^3	E6	E^3	I12	I^3
45	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
46	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
47	1	C4	C^4	E8	E^4	J2	J^0
48	1	C5	C^5	E10	E^5	J6	J^1
49	1	C6	C^6	E12	E^6	J10	J^2
50	1	C7	C^7	E14	E^7	J12	J^3
51	-	GND	-	GND	-	GND	-
52	-	TMS	-	TMS	-	TMS	-
53	1	C8	C^8	F0	F^0	K12	K^3
54	1	C9	C^9	F2	F^1	K10	K^2
55	1	C10	C^10	F4	F^2	K6	K^1
56	1	C11	C^11	F6	F^3	K2	K^0
57	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
58	1	C12	C^12	F8	F^4	L12	L^3
59	1	C13	C^13	F10	F^5	L10	L^2
60	1	C14	C^14	F12	F^6	L6	L^1
61	1	C15	C^15	F13	F^7	L4	L^0
62*	1	I	-	I	-	I	-
63	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
64	1	D15	D^15	G14	G^7	M4	M^0
65	1	D14	D^14	G12	G^6	M6	M^1
66	1	D13	D^13	G10	G^5	M10	M^2
67	1	D12	D^12	G8	G^4	M12	M^3
68	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
69	1	D11	D^11	G6	G^3	N2	N^0
70	1	D10	D^10	G5	G^2	N6	N^1
71	1	D9	D^9	G4	G^1	N10	N^2
72	1	D8	D^8	G2	G^0	N12	N^3
73*	1	I	-	I	-	I	-
74	-	TDO	-	TDO	-	TDO	-
75	-	VCC	-	VCC	-	VCC	-
76	-	GND	-	GND	-	GND	-
77*	1	I	-	I	-	I	-
78	1	D7	D^7	H13	H^7	O12	O^3
79	1	D6	D^6	H12	H^6	O10	O^2
80	1	D5	D^5	H10	H^5	O6	O^1
81	1	D4	D^4	H8	H^4	O2	O^0
82	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-

**ispMACH 4064V/B/C/Z, 4128V/B/C/Z, 4256V/B/C/Z Logic Signal Connections:
100-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4064V/B/C/Z		ispMACH 4128V/B/C/Z		ispMACH 4256V/B/C/Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
83	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
84	1	D3	D^3	H6	H^3	P12	P^3
85	1	D2	D^2	H4	H^2	P10	P^2
86	1	D1	D^1	H2	H^1	P6	P^1
87	1	D0/GOE1	D^0	H0/GOE1	H^0	P2/OE1	P^0
88	1	CLK3/I	-	CLK3/I	-	CLK3/I	-
89	0	CLK0/I	-	CLK0/I	-	CLK0/I	-
90	-	VCC	-	VCC	-	VCC	-
91	0	A0/GOE0	A^0	A0/GOE0	A^0	A2/GOE0	A^0
92	0	A1	A^1	A2	A^1	A6	A^1
93	0	A2	A^2	A4	A^2	A10	A^2
94	0	A3	A^3	A6	A^3	A12	A^3
95	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
96	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
97	0	A4	A^4	A8	A^4	B2	B^0
98	0	A5	A^5	A10	A^5	B6	B^1
99	0	A6	A^6	A12	A^6	B10	B^2
100	0	A7	A^7	A14	A^7	B12	B^3

*This pin is input only.

ispMACH 4128V/B/C Logic Signal Connections: 128-Pin TQFP

Pin Number	Bank Number	ispMACH 4128V/B/C	
		GLB/MC/Pad	ORP
1	0	GND	-
2	0	TDI	-
3	0	VCCO (Bank 0)	-
4	0	B0	B^0
5	0	B1	B^1
6	0	B2	B^2
7	0	B4	B^3
8	0	B5	B^4
9	0	B6	B^5
10	0	GND (Bank 0)	-
11	0	B8	B^6
12	0	B9	B^7
13	0	B10	B^8
14	0	B12	B^9
15	0	B13	B^10
16	0	B14	B^11
17	0	VCCO (Bank 0)	-
18	0	C14	C^11

ispMACH 4128V/B/C Logic Signal Connections: 128-Pin TQFP (Cont.)

Pin Number	Bank Number	ispMACH 4128V/B/C	
		GLB/MC/Pad	ORP
62	1	E10	E^8
63	1	E12	E^9
64	1	E14	E^11
65	1	GND	-
66	1	TMS	-
67	1	VCCO (Bank 1)	-
68	1	F0	F^0
69	1	F1	F^1
70	1	F2	F^2
71	1	F4	F^3
72	1	F5	F^4
73	1	F6	F^5
74	1	GND (Bank 1)	-
75	1	F8	F^6
76	1	F9	F^7
77	1	F10	F^8
78	1	F12	F^9
79	1	F13	F^10
80	1	F14	F^11
81	1	VCCO (Bank 1)	-
82	1	G14	G^11
83	1	G13	G^10
84	1	G12	G^9
85	1	G10	G^8
86	1	G9	G^7
87	1	G8	G^6
88	1	GND (Bank 1)	-
89	1	G6	G^5
90	1	G5	G^4
91	1	G4	G^3
92	1	G2	G^2
93	1	G0	G^0
94	1	VCCO (Bank 1)	-
95	1	TDO	-
96	1	VCC	-
97	1	GND	-
98	1	H14	H^11
99	1	H13	H^10
100	1	H12	H^9
101	1	H10	H^8
102	1	H9	H^7
103	1	H8	H^6
104	1	GND (Bank 1)	-

**ispMACH 4256V/B/C, 4384V/B/C, 4512V/B/C Logic Signal Connections:
256-Ball ftBGA/fpBGA (Cont.)**

Ball Number	I/O Bank	ispMACH 4256V/B/C 128-I/O		ispMACH 4256V/B/C 160-I/O		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
R5	0	NC	-	NC	-	NC	-	L4	L^1
T5	0	NC	-	NC	-	I2	I^1	L8	L^2
R6	0	NC	-	NC	-	I0	I^0	L12	L^3
T6	0	NC	-	H14	H^9	G12	G^6	M8	M^2
N7	0	NC	-	H12	H^8	G14	G^7	M12	M^3
P7	0	H14	H^7	H10	H^7	L14	L^7	P14	P^7
R7	0	H12	H^6	H9	H^6	L12	L^6	P12	P^6
L8	0	H10	H^5	H8	H^5	L10	L^5	P10	P^5
T7	0	H8	H^4	H6	H^4	L8	L^4	P8	P^4
M8	0	H6	H^3	H4	H^3	L6	L^3	P6	P^3
N8	0	H4	H^2	H2	H^2	L4	L^2	P4	P^2
R8	0	H2	H^1	H1	H^1	L2	L^1	P2	P^1
P8	0	H0	H^0	H0	H^0	L0	L^0	P0	P^0
-	-	GND	-	GND	-	GND	-	GND	-
T8	0	CLK1/I	-	CLK1/I	-	CLK1/I	-	CLK1/I	-
-	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
N9	1	CLK2/I	-	CLK2/I	-	CLK2/I	-	CLK2/I	-
-	-	VCC	-	VCC	-	VCC	-	VCC	-
P9	1	I0	I^0	I0	I^0	M0	M^0	AX0	AX^0
R9	1	I2	I^1	I1	I^1	M2	M^1	AX2	AX^1
T9	1	I4	I^2	I2	I^2	M4	M^2	AX4	AX^2
T10	1	I6	I^3	I4	I^3	M6	M^3	AX6	AX^3
R10	1	I8	I^4	I6	I^4	M8	M^4	AX8	AX^4
M9	1	I10	I^5	I8	I^5	M10	M^5	AX10	AX^5
P10	1	I12	I^6	I9	I^6	M12	M^6	AX12	AX^6
L9	1	I14	I^7	I10	I^7	M14	M^7	AX14	AX^7
N10	1	NC	-	I12	I^8	BX14	BX^7	DX0	DX^0
T11	1	NC	-	I14	I^9	BX12	BX^6	DX4	DX^1
R11	1	NC	-	NC	-	P0	P^0	EX0	EX^0
T12	1	NC	-	NC	-	P2	P^1	EX4	EX^1
N12	1	NC	-	NC	-	NC	-	EX8	EX^2
-	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
-	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
R12	1	NC	-	NC	-	NC	-	EX12	EX^3
T13	1	NC	-	J0	J^0	BX10	BX^5	DX8	DX^2
P12	1	NC	-	J1	J^1	BX8	BX^4	DX12	DX^3
M10	1	J0	J^0	J2	J^2	N0	N^0	BX0	BX^0
R13	1	J2	J^1	J4	J^3	N2	N^1	BX2	BX^1
L10	1	J4	J^2	J6	J^4	N4	N^2	BX4	BX^2
T14	1	J6	J^3	J8	J^5	N6	N^3	BX6	BX^3
M11	1	J8	J^4	J9	J^6	N8	N^4	BX8	BX^4

ispMACH 4000ZC (1.8V, Zero Power) Industrial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4064ZC	LC4064ZC-5M132I	64	1.8	5	csBGA	132	64	I
	LC4064ZC-75M132I	64	1.8	7.5	csBGA	132	64	I
	LC4064ZC-5T100I	64	1.8	5	TQFP	100	64	I
	LC4064ZC-75T100I	64	1.8	7.5	TQFP	100	64	I
	LC4064ZC-5M56I	64	1.8	5	csBGA	56	34	I
	LC4064ZC-75M56I	64	1.8	7.5	csBGA	56	34	I
	LC4064ZC-5T48I	64	1.8	5	TQFP	48	32	I
	LC4064ZC-75T48I	64	1.8	7.5	TQFP	48	32	I
LC4128ZC	LC4128ZC-75M132I	128	1.8	7.5	csBGA	132	96	I
	LC4128ZC-75T100I	128	1.8	7.5	TQFP	100	64	I
LC4256ZC	LC4256ZC-75T176I	256	1.8	7.5	TQFP	176	128	I
	LC4256ZC-75M132I	256	1.8	7.5	csBGA	132	96	I
	LC4256ZC-75T100I	256	1.8	7.5	TQFP	100	64	I

ispMACH 4000ZC (1.8V, Zero Power) Extended Temperature Devices

Family	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-75T48E	32	1.8	7.5	TQFP	48	32	E
LC4064ZC	LC4064ZC-75T100E	64	1.8	7.5	TQFP	100	64	E
	LC4064ZC-75T48E	64	1.8	7.5	TQFP	48	32	E
LC4128ZC	LC4128ZC-75T100E	128	1.8	7.5	TQFP	100	64	E
LC4256ZC	LC4256ZC-75T176E	256	1.8	7.5	TQFP	176	128	E
	LC4256ZC-75T100E	256	1.8	7.5	TQFP	100	64	E

ispMACH 4000C (1.8V) Commercial Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032C	LC4032C-25T48C	32	1.8	2.5	TQFP	48	32	C
	LC4032C-5T48C	32	1.8	5	TQFP	48	32	C
	LC4032C-75T48C	32	1.8	7.5	TQFP	48	32	C
	LC4032C-25T44C	32	1.8	2.5	TQFP	44	30	C
	LC4032C-5T44C	32	1.8	5	TQFP	44	30	C
	LC4032C-75T44C	32	1.8	7.5	TQFP	44	30	C
LC4064C	LC4064C-25T100C	64	1.8	2.5	TQFP	100	64	C
	LC4064C-5T100C	64	1.8	5	TQFP	100	64	C
	LC4064C-75T100C	64	1.8	7.5	TQFP	100	64	C
	LC4064C-25T48C	64	1.8	2.5	TQFP	48	32	C
	LC4064C-5T48C	64	1.8	5	TQFP	48	32	C
	LC4064C-75T48C	64	1.8	7.5	TQFP	48	32	C
	LC4064C-25T44C	64	1.8	2.5	TQFP	44	30	C
	LC4064C-5T44C	64	1.8	5	TQFP	44	30	C
	LC4064C-75T44C	64	1.8	7.5	TQFP	44	30	C

ispMACH 4000B (2.5V) Industrial Devices

Family	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032B	LC4032B-5T48I	32	2.5	5	TQFP	48	32	I
	LC4032B-75T48I	32	2.5	7.5	TQFP	48	32	I
	LC4032B-10T48I	32	2.5	10	TQFP	48	32	I
	LC4032B-5T44I	32	2.5	5	TQFP	44	30	I
	LC4032B-75T44I	32	2.5	7.5	TQFP	44	30	I
	LC4032B-10T44I	32	2.5	10	TQFP	44	30	I
LC4064B	LC4064B-5T100I	64	2.5	5	TQFP	100	64	I
	LC4064B-75T100I	64	2.5	7.5	TQFP	100	64	I
	LC4064B-10T100I	64	2.5	10	TQFP	100	64	I
	LC4064B-5T48I	64	2.5	5	TQFP	48	32	I
	LC4064B-75T48I	64	2.5	7.5	TQFP	48	32	I
	LC4064B-10T48I	64	2.5	10	TQFP	48	32	I
	LC4064B-5T44I	64	2.5	5	TQFP	44	30	I
	LC4064B-75T44I	64	2.5	7.5	TQFP	44	30	I
	LC4064B-10T44I	64	2.5	10	TQFP	44	30	I
LC4128B	LC4128B-5T128I	128	2.5	5	TQFP	128	92	I
	LC4128B-75T128I	128	2.5	7.5	TQFP	128	92	I
	LC4128B-10T128I	128	2.5	10	TQFP	128	92	I
	LC4128B-5T100I	128	2.5	5	TQFP	100	64	I
	LC4128B-75T100I	128	2.5	7.5	TQFP	100	64	I
	LC4128B-10T100I	128	2.5	10	TQFP	100	64	I
LC4256B	LC4256B-5FT256AI	256	2.5	5	ftBGA	256	128	I
	LC4256B-75FT256AI	256	2.5	7.5	ftBGA	256	128	I
	LC4256B-10FT256AI	256	2.5	10	ftBGA	256	128	I
	LC4256B-5FT256BI	256	2.5	5	ftBGA	256	160	I
	LC4256B-75FT256BI	256	2.5	7.5	ftBGA	256	160	I
	LC4256B-10FT256BI	256	2.5	10	ftBGA	256	160	I
	LC4256B-5F256AI ¹	256	2.5	5	fpBGA	256	128	I
	LC4256B-75F256AI ¹	256	2.5	7.5	fpBGA	256	128	I
	LC4256B-10F256AI ¹	256	2.5	10	fpBGA	256	128	I
	LC4256B-5F256BI ¹	256	2.5	5	fpBGA	256	160	I
	LC4256B-75F256BI ¹	256	2.5	7.5	fpBGA	256	160	I
	LC4256B-10F256BI ¹	256	2.5	10	fpBGA	256	160	I
	LC4256B-5T176I	256	2.5	5	TQFP	176	128	I
	LC4256B-75T176I	256	2.5	7.5	TQFP	176	128	I
	LC4256B-10T176I	256	2.5	10	TQFP	176	128	I
	LC4256B-5T100I	256	2.5	5	TQFP	100	64	I
	LC4256B-75T100I	256	2.5	7.5	TQFP	100	64	I
	LC4256B-10T100I	256	2.5	10	TQFP	100	64	I

ispMACH 4000B (2.5V) Industrial Devices (Cont.)

Family	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4384B	LC4384B-5FT256I	384	2.5	5	ftBGA	256	192	I
	LC4384B-75FT256I	384	2.5	7.5	ftBGA	256	192	I
	LC4384B-10FT256I	384	2.5	10	ftBGA	256	192	I
	LC4384B-5F256I ¹	384	2.5	5	fpBGA	256	192	I
	LC4384B-75F256I ¹	384	2.5	7.5	fpBGA	256	192	I
	LC4384B-10F256I ¹	384	2.5	10	fpBGA	256	192	I
	LC4384B-5T176I	384	2.5	5	TQFP	176	128	I
	LC4384B-75T176I	384	2.5	7.5	TQFP	176	128	I
	LC4384B-10T176I	384	2.5	10	TQFP	176	128	I
LC4512B	LC4512B-5FT256I	512	2.5	5	ftBGA	256	208	I
	LC4512B-75FT256I	512	2.5	7.5	ftBGA	256	208	I
	LC4512B-10FT256I	512	2.5	10	ftBGA	256	208	I
	LC4512B-5F256I ¹	512	2.5	5	fpBGA	256	208	I
	LC4512B-75F256I ¹	512	2.5	7.5	fpBGA	256	208	I
	LC4512B-10F256I ¹	512	2.5	10	fpBGA	256	208	I
	LC4512B-5T176I	512	2.5	5	TQFP	176	128	I
	LC4512B-75T176I	512	2.5	7.5	TQFP	176	128	I
	LC4512B-10T176I	512	2.5	10	TQFP	176	128	I

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000V (3.3V) Commercial Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032V	LC4032V-25T48C	32	3.3	2.5	TQFP	48	32	C
	LC4032V-5T48C	32	3.3	5	TQFP	48	32	C
	LC4032V-75T48C	32	3.3	7.5	TQFP	48	32	C
	LC4032V-25T44C	32	3.3	2.5	TQFP	44	30	C
	LC4032V-5T44C	32	3.3	5	TQFP	44	30	C
	LC4032V-75T44C	32	3.3	7.5	TQFP	44	30	C
LC4064V	LC4064V-25T100C	64	3.3	2.5	TQFP	100	64	C
	LC4064V-5T100C	64	3.3	5	TQFP	100	64	C
	LC4064V-75T100C	64	3.3	7.5	TQFP	100	64	C
	LC4064V-25T48C	64	3.3	2.5	TQFP	48	32	C
	LC4064V-5T48C	64	3.3	5	TQFP	48	32	C
	LC4064V-75T48C	64	3.3	7.5	TQFP	48	32	C
	LC4064V-25T44C	64	3.3	2.5	TQFP	44	30	C
	LC4064V-5T44C	64	3.3	5	TQFP	44	30	C
	LC4064V-75T44C	64	3.3	7.5	TQFP	44	30	C

ispMACH 4000V (3.3V) Lead-Free Commercial Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032V	LC4032V-25TN48C	32	3.3	2.5	Lead-free TQFP	48	32	C
	LC4032V-5TN48C	32	3.3	5	Lead-free TQFP	48	32	C
	LC4032V-75TN48C	32	3.3	7.5	Lead-free TQFP	48	32	C
	LC4032V-25TN44C	32	3.3	2.5	Lead-free TQFP	44	30	C
	LC4032V-5TN44C	32	3.3	5	Lead-free TQFP	44	30	C
	LC4032V-75TN44C	32	3.3	7.5	Lead-free TQFP	44	30	C
LC4064V	LC4064V-25TN100C	64	3.3	2.5	Lead-free TQFP	100	64	C
	LC4064V-5TN100C	64	3.3	5	Lead-free TQFP	100	64	C
	LC4064V-75TN100C	64	3.3	7.5	Lead-free TQFP	100	64	C
	LC4064V-25TN48C	64	3.3	2.5	Lead-free TQFP	48	32	C
	LC4064V-5TN48C	64	3.3	5	Lead-free TQFP	48	32	C
	LC4064V-75TN48C	64	3.3	7.5	Lead-free TQFP	48	32	C
	LC4064V-25TN44C	64	3.3	2.5	Lead-free TQFP	44	30	C
	LC4064V-5TN44C	64	3.3	5	Lead-free TQFP	44	30	C
	LC4064V-75TN44C	64	3.3	7.5	Lead-free TQFP	44	30	C
LC4128V	LC4128V-27TN144C	128	3.3	2.7	Lead-free TQFP	144	96	C
	LC4128V-5TN144C	128	3.3	5	Lead-free TQFP	144	96	C
	LC4128V-75TN144C	128	3.3	7.5	Lead-free TQFP	144	96	C
	LC4128V-27TN128C	128	3.3	2.7	Lead-free TQFP	128	92	C
	LC4128V-5TN128C	128	3.3	5	Lead-free TQFP	128	92	C
	LC4128V-75TN128C	128	3.3	7.5	Lead-free TQFP	128	92	C
	LC4128V-27TN100C	128	3.3	2.7	Lead-free TQFP	100	64	C
	LC4128V-5TN100C	128	3.3	5	Lead-free TQFP	100	64	C
	LC4128V-75TN100C	128	3.3	7.5	Lead-free TQFP	100	64	C

ispMACH 4000V (3.3V) Lead-Free Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4256V	LC4256V-3FTN256AC	256	3.3	3	Lead-free ftBGA	256	128	C
	LC4256V-5FTN256AC	256	3.3	5	Lead-free ftBGA	256	128	C
	LC4256V-75FTN256AC	256	3.3	7.5	Lead-free ftBGA	256	128	C
	LC4256V-3FTN256BC	256	3.3	3	Lead-free ftBGA	256	160	C
	LC4256V-5FTN256BC	256	3.3	5	Lead-free ftBGA	256	160	C
	LC4256V-75FTN256BC	256	3.3	7.5	Lead-free ftBGA	256	160	C
	LC4256V-3FN256AC ¹	256	3.3	3	Lead-free fpBGA	256	128	C
	LC4256V-5FN256AC ¹	256	3.3	5	Lead-free fpBGA	256	128	C
	LC4256V-75FN256AC ¹	256	3.3	7.5	Lead-free fpBGA	256	128	C
	LC4256V-3FN256BC ¹	256	3.3	3	Lead-free fpBGA	256	160	C
	LC4256V-5FN256BC ¹	256	3.3	5	Lead-free fpBGA	256	160	C
	LC4256V-75FN256BC ¹	256	3.3	7.5	Lead-free fpBGA	256	160	C
	LC4256V-3TN176C	256	3.3	3	Lead-free TQFP	176	128	C
	LC4256V-5TN176C	256	3.3	5	Lead-free TQFP	176	128	C
	LC4256V-75TN176C	256	3.3	7.5	Lead-free TQFP	176	128	C
	LC4256V-3TN144C	256	3.3	3	Lead-free TQFP	144	96	C
	LC4256V-5TN144C	256	3.3	5	Lead-free TQFP	144	96	C
	LC4256V-75TN144C	256	3.3	7.5	Lead-free TQFP	144	96	C
	LC4256V-3TN100C	256	3.3	3	Lead-free TQFP	100	64	C
	LC4256V-5TN100C	256	3.3	5	Lead-free TQFP	100	64	C
	LC4256V-75TN100C	256	3.3	7.5	Lead-free TQFP	100	64	C
LC4384V	LC4384V-35FTN256C	384	3.3	3.5	Lead-free ftBGA	256	192	C
	LC4384V-5FTN256C	384	3.3	5	Lead-free ftBGA	256	192	C
	LC4384V-75FTN256C	384	3.3	7.5	Lead-free ftBGA	256	192	C
	LC4384V-35FN256C ¹	384	3.3	3.5	Lead-free fpBGA	256	192	C
	LC4384V-5FN256C ¹	384	3.3	5	Lead-free fpBGA	256	192	C
	LC4384V-75FN256C ¹	384	3.3	7.5	Lead-free fpBGA	256	192	C
	LC4384V-35TN176C	384	3.3	3.5	Lead-free TQFP	176	128	C
	LC4384V-5TN176C	384	3.3	5	Lead-free TQFP	176	128	C
	LC4384V-75TN176C	384	3.3	7.5	Lead-free TQFP	176	128	C
LC4512V	LC4512V-35FTN256C	512	3.3	3.5	Lead-free ftBGA	256	208	C
	LC4512V-5FTN256C	512	3.3	5	Lead-free ftBGA	256	208	C
	LC4512V-75FTN256C	512	3.3	7.5	Lead-free ftBGA	256	208	C
	LC4512V-35FN256C ¹	512	3.3	3.5	Lead-free fpBGA	256	208	C
	LC4512V-5FN256C ¹	512	3.3	5	Lead-free fpBGA	256	208	C
	LC4512V-75FN256C ¹	512	3.3	7.5	Lead-free fpBGA	256	208	C
	LC4512V-35TN176C	512	3.3	3.5	Lead-free TQFP	176	128	C
	LC4512V-5TN176C	512	3.3	5	Lead-free TQFP	176	128	C
	LC4512V-75TN176C	512	3.3	7.5	Lead-free TQFP	176	128	C

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.